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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/567,358	02/06/2006	Yasukazu Nakata	Q92997	9855
23373	7590	05/23/2007	EXAMINER	
SUGHRUE MION, PLLC 2100 PENNSYLVANIA AVENUE, N.W. SUITE 800 WASHINGTON, DC 20037			LEVI, DAMEON E	
			ART UNIT	PAPER NUMBER
			2841	
			MAIL DATE	DELIVERY MODE
			05/23/2007	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No.	Applicant(s)
	10/567,358	NAKATA ET AL.
	Examiner	Art Unit
	Dameon E. Levi	2841

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 20 December 2006.
 2a) This action is FINAL. 2b) This action is non-final.
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 1-4 is/are pending in the application.
 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
 5) Claim(s) _____ is/are allowed.
 6) Claim(s) 1-4 is/are rejected.
 7) Claim(s) _____ is/are objected to.
 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.
 10) The drawing(s) filed on 06 February 2006 is/are: a) accepted or b) objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) Notice of References Cited (PTO-892)
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
 3) Information Disclosure Statement(s) (PTO/SB/08)
 Paper No(s)/Mail Date _____

4) Interview Summary (PTO-413)
 Paper No(s)/Mail Date. _____
 5) Notice of Informal Patent Application
 6) Other: _____

DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-4 are rejected under 35 U.S.C. 102(b) as being anticipated by Ikefuji et al US Patent 6404644.

Regarding claim 1, Ikefuji et al discloses a flip chip mounting substrate which comprises: an electronic circuit composed of a circuit line(element 12, Figs 1-4, 32, Fig 5, 52, 57, Fig 6) and plural mounting pads(element 12a,12b, Figs 1-4) connected to both ends of the circuit line formed on one surface of a base sheet(element 10, Figs 1-4), wherein the plural mounting pads are faced each other and spaced a pad clearance gap apart, and one or more semiconductor mounting paste guide paths(element 16, Figs 1-4) are formed in the mounting pads.

Regarding claim 2, Ikefuji et al discloses wherein a width of the semiconductor mounting paste guide path is in the range from 50 to 600 um(element 16, Figs 1-4).

Regarding claim 3, Ikefuji et al discloses wherein a broad section(element 19b, Figs 1-4) for pressing out and spreading uniformly the semiconductor mounting paste(element 19, Figs 1-4) to connecting to an IC chip is formed in a part of the pad clearance gap.

Regarding claim 4, Ikefuji et al discloses wherein a thin film layer (element 19a, Figs 1-4) is formed in center section of the broad section.

Response to Arguments

Applicant's arguments filed 12/20/2006 have been fully considered but they are not persuasive.

Applicant argues on page 2, that the prior art of record fails to disclose or suggest plural mounting pads connected to both ends of the circuit line formed on one surface of a base sheet wherein the plural mounting pads are faced each other and spaced a pad clearance gap apart, and one or more semiconductor mounting paste guide paths are formed in the mounting pads.

In response, the Office asserts that these features are shown as illustrated in claim 1 above, and elements 12a and 12b are construed by the Office as being mounting pads since the IC chip 11 is mounted thereon by way of solder bumps 16, Further the elements are deemed as facing each other on the mounting substrate (see Figs 1-4) and are spaced a pad gap apart.

Applicant also argues, on page 3, that the prior art of record does not teach or describe semiconductor mounting paste. In response, the Office asserts that the semiconductor mounting paste is deemed as being a paste or adhesive with which a semiconductor is mounted to a surface. In the instant case, the anisotropic conducting adhesive film is construed by the Office as serving the same purpose of being a paste or adhesive with which a semiconductor is mounted to a surface and is deemed as an equivalent. This rejection is maintained by the Office.

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dameon E. Levi whose telephone number is (571) 272-2105. The examiner can normally be reached on Mon.-Thurs. (9:00 - 5:00) IFP, Fridays Telework.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Dean Reichard can be reached on (571) 272-1984. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

Dameon E Levi
Examiner
Art Unit 2841

DEL


DEAN A. REICHARD
SUPERVISORY PATENT EXAMINER
TECHNOLOGY CENTER 2800
5/18/07